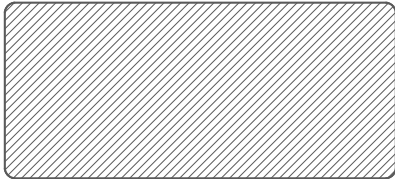
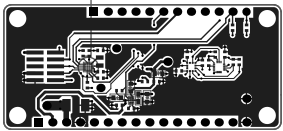



Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

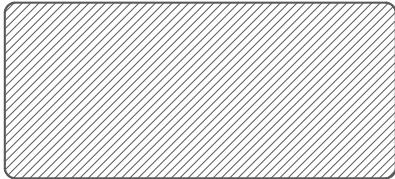


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

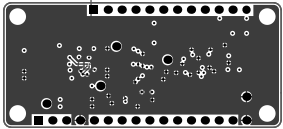



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

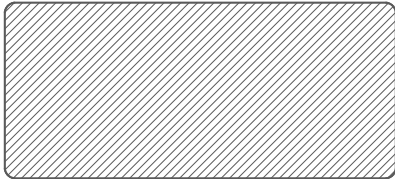


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

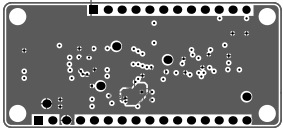



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

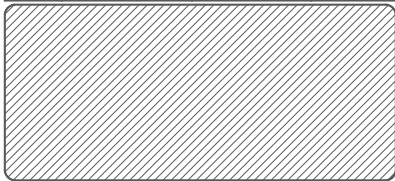


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

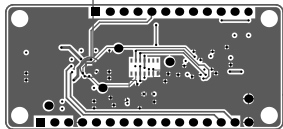



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3,5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4,2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4,2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4,2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3,5	
11	Bottom Overlay				

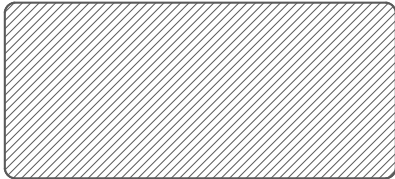


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

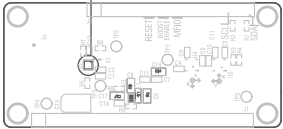



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

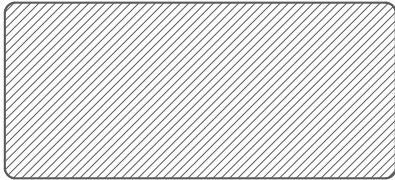


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

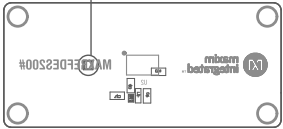



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

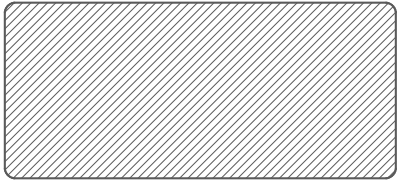


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

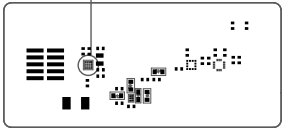



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

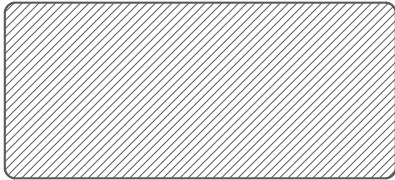


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

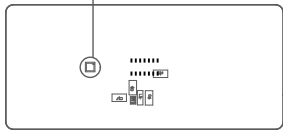



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

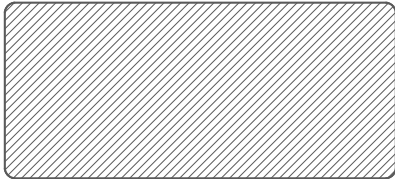


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

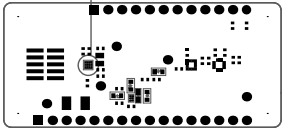



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

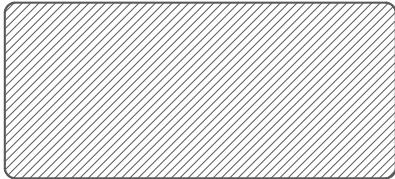


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

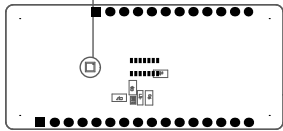



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

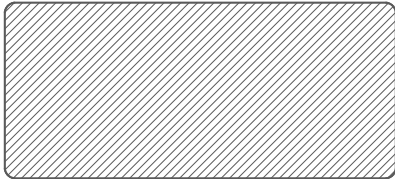


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS




 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

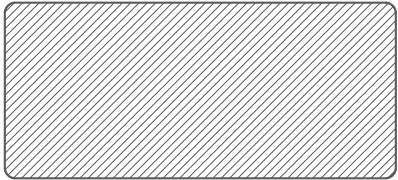


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS




 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

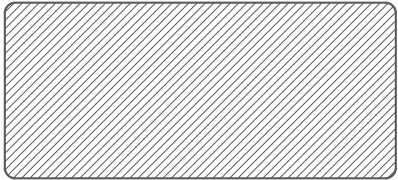


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

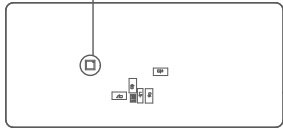



 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

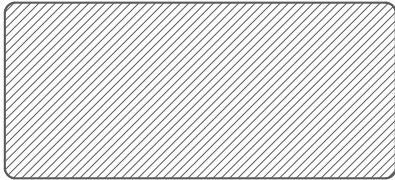


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

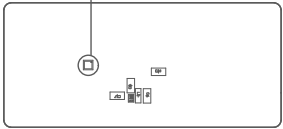



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

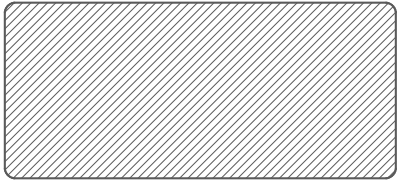


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

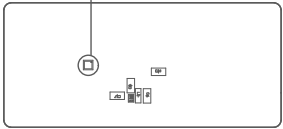



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

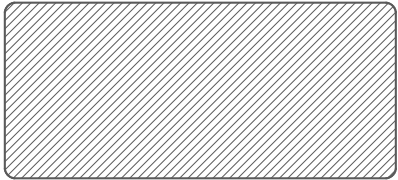


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS




 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

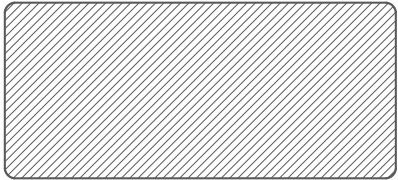


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

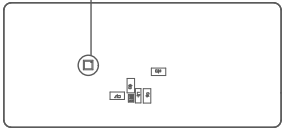



 Maxim Integrated™ 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

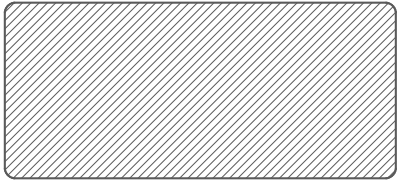


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

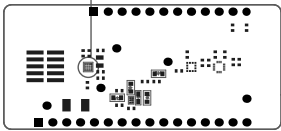



 Maxim Integrated™ 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

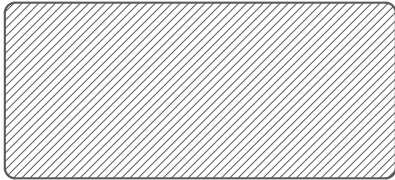


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

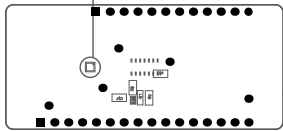



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

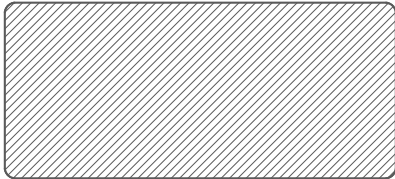


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

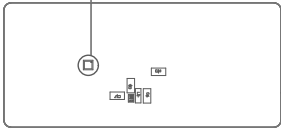



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				



· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

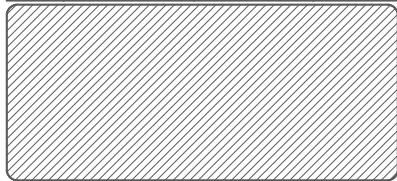


 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

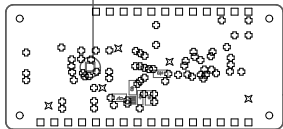
123456


Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
○	4	100.00mil (2.540mm)	PTH	Round	Component Side - Solder Side	Pad	Rounded	c0h254			
⊗	5	32.00mil (0.813mm)	PTH	Round	Component Side - Solder Side	Pad	Rounded	c152h81mx0			
□	28	40.00mil (1.016mm)	PTH	Round	Component Side - Solder Side	Pad	(Mixed)	(Mixed)			
⊙	72	7.87mil (0.200mm)	PTH	Round	Component Side - Solder Side	Via	Rounded	v41h20m0mx0			
109 Total											

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				



- MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS



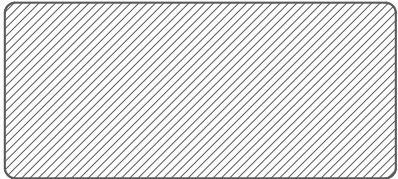
 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

123456

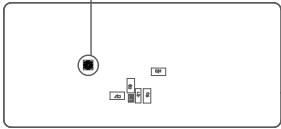
123456


Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
⌘	4	4.00mil (0.102mm)	PTH	Round	Component Side - GroundPlane	Via	Rounded	v20h10m20			
	4 Total										

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				



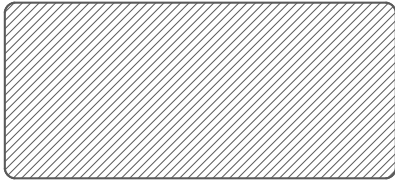
- MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS



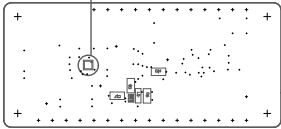
 Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:


123456

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				

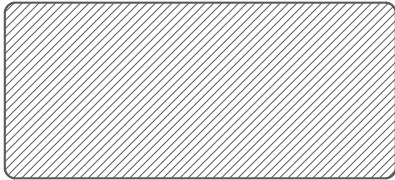


· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS

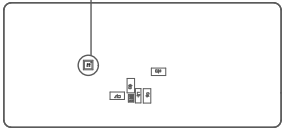



 maxim integrated™ Maxim Integrated 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.010mm	3.5	
3	Component Side	Copper	0.036mm		
4	Dielectric 1	FR-4	0.472mm	4.2	
5	GroundPlane	Copper	0.036mm		
6	Dielectric 3	FR-4	0.472mm	4.2	
7	PowerPlane	Copper	0.036mm		
8	Dielectric 4	FR-4	0.472mm	4.2	
9	Solder Side	Copper	0.036mm		
10	Bottom Solder	Solder Resist	0.010mm	3.5	
11	Bottom Overlay				



· MICRO VIA IN PAD (STACKED MICRO VIA)
PLATED AND PLANARIZED, WLP (BGA) MOUNTING PADS



 Maxim Integrated™ 160 Rio Robles San Jose, CA 95134 (408) 733-7600	ENGINEER:	TITLE:	
	PCB DESIGNER:		
	DATE:	PART NO.:	REV.:
	FILE NAME: ME11_OS24_FeatherWing.PcbDoc	DWG NO.:	SCALE: